

**REMARKS**

Reconsideration of claims 1-17 and 19-24 is respectfully requested. Claim 21 is amended as suggested.

The rejection of claims 1-2, 6, 11, 15-17 and 20-21 under 35 U.S.C§102(b) as being anticipated by Cheng et al., US 5,901,038 (the '338 patent) is respectfully traversed. In paragraph 6, the Office Action states that the '038 patent discloses a connector with “second ventilation openings... disposed under the pain of arms and enable air to flow between the motherboard and the electronic module”. Applicants disagree with this interpretation of the teachings of the '038 patent because the '038 patent does not describe a connector that is used to connect an electronic module to a motherboard. Rather, the '038 patent describes a table-like mounting structure that is used to couple a power supply 140 to a motherboard 125. See, Abstract and Figs. 1-6, 11-12 and 14-16. The mounting structure can also include a finned heat sink 1100/1200 upon which the power supply 140 sits. The heat sink is used to dissipate heat generated by the power supply. There is no teaching or even any suggestion that the mounting structure can be used “as is” or modified to connect an electronic module to a motherboard. In fact, one skilled in the art would not look to the '038 patent to address the problem solved by Applicants because the amount of heat generated by a power supply is substantially greater than that generated by an electronic module. Hence, the need for the attachment of heatsinks 1100/1200 to the mounting structure.

A proper rejection under 35 U.S.C§102(b) requires that all of the claim limitations be present in the reference. The '038 patent does not disclose a “main body [that] has contacts ... adapted for electrical connection to the mother board and an opposite end adapted for electrical connection with the electrical conductive pads of the electronic module”, as claimed. It appears the Office Action takes the position that a power supply is a type of electronic module. That position is technically incorrect. As described on page 1 of the Application, an “electronic module comprises a card-like substrate, electronic chips, such as memory chips, [which can be] mounted on both ... surfaces of the substrate. See, also page 2 for a description of an electronic module with high performance chips used in notebook computers. Accordingly, Applicants respectfully request that the rejection be withdrawn. In view of the above, each of the presently pending claims in this application is believed to be in condition for allowance.

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Applicants believe no fee is due with this response. However, if a fee is due, please charge our Deposit Account No. 22-0185, under Order No. 22004-00003-US from which the undersigned is authorized to draw.

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Respectfully submitted,

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